



**FEATURES**

- Circular active area
- TO-39, 3 pin package
- Excellent stability after EUV exposure
- Windowless package for responsivity to 1nm

Dimensions are in inch [metric] units.

**ELECTRO-OPTICAL CHARACTERISTICS AT 25°C**

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Active Area			Ø2.5		mm <sup>2</sup>
Responsivity, $\mathcal{R}$	See attached graph				
Shunt Resistance, Rsh	@ ± 10 mV	20			MOhms
Reverse Breakdown Voltage, $V_R$	$I_R = 1 \mu A$		20		Volts
Capacitance, C	$V_R = 0V$			1	nF
Response Time, tr	$R_L = 50\Omega, V_R = 15V$		1	2	nsec

**THERMAL PARAMETERS**

STORAGE AND OPERATING TEMPERATURE RANGE	
Ambient	-10° TO 40°C
Nitrogen or Vacuum	-20°C TO 80°C
Maximum Junction Temperature	70°C
Lead Soldering Temperature <sup>1</sup>	260°C

<sup>1</sup>0.08" from case for 10 seconds

